Dual Self-Protected Low-Side Driver with Temperature and Current Limit

NCV8402D, NCV8402AD

NCV8402D/AD is a dual protected Low-Side Smart Discrete device. The protection features include overcurrent, overtemperature, ESD and integrated Drain-to-Gate clamping for overvoltage protection. This device offers protection and is suitable for harsh automotive environments.

Features

- Short-Circuit Protection
- Thermal Shutdown with Automatic Restart
- Overvoltage Protection
- Integrated Clamp for Inductive Switching
- ESD Protection
- dV/dt Robustness
- Analog Drive Capability (Logic Level Input)
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Switch a Variety of Resistive, Inductive and Capacitive Loads
- Can Replace Electromechanical Relays and Discrete Circuits
- Automotive / Industrial

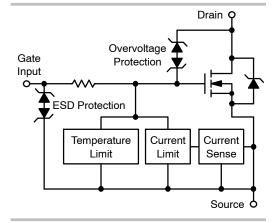


ON Semiconductor®

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V _{(BR)DSS} (Clamped)	R _{DS(ON)} TYP	I _D MAX
42 V	165 mΩ @ 10 V	2.0 A*

^{*}Max current limit value is dependent on input



MARKING DIAGRAM



SO-8 CASE 751 STYLE 11

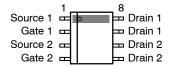


xxxxxx = V8402D or 8402AD A = Assembly Location

L = Wafer Lot Y = Year W = Work Week

= Pb-Free Package

PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping [†]
NCV8402DDR2G		2500/Tape & Reel
NCV8402ADDR20	G (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating			Value	Unit
Drain-to-Source Voltage Internally Clamped		V_{DSS}	42	V
Drain-to-Gate Voltage Internally Clamped	$(R_G = 1.0 M\Omega)$	V_{DGR}	42	V
Gate-to-Source Voltage		V _{GS}	±14	V
Continuous Drain Current			Internally Limited	
Total Power Dissipation	@ T _A = 25°C (Note 1) @ T _A = 25°C (Note 2)	P _D	0.8 1.62	W
Maximum Continuous Drain, both channels on	@ T _A = 25°C (Note 1) @ T _A = 25°C (Note 2)	I _D	1.87 2.65	А
Thermal Resistance	Junction-to-Ambient Steady State (Note 1) Junction-to-Ambient Steady State (Note 2)	$R_{ hetaJA} \ R_{ hetaJA}$	157 77	°C/W
Single Pulse Drain-to–Source Avalanche Energy (V _{DD} = 32 V, V _G = 5.0 V, I _{PK} = 1.0 A, L = 300 mH, R _{G(ext)} = 25 Ω)			150	mJ
Load Dump Voltage (V _{GS} =	(V _{GS} = 0 and 10 V, R _I = 2.0 Ω , R _L = 9.0 Ω , t _d = 400 ms)			V
Operating Junction and Storage Temperature			-55 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface-mounted onto min pad FR4 PCB, (Cu area = 40 sq. mm, 1 oz.).

2. Surface-mounted onto 1" sq. FR4 board (Cu area = 625 sq. mm, 2 oz.).

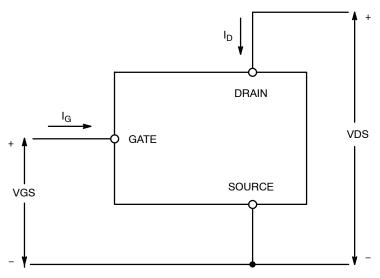


Figure 1. Voltage and Current Convention

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Test Condition	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	V _{(BR)DSS}	42	46	55	V
(Note 3)	V _{GS} = 0 V, I _D = 10 mA, T _J = 150°C (Note 5)		40	45	55	
Zero Gate Voltage Drain Current	V _{GS} = 0 V, V _{DS} = 32 V, T _J = 25°C	I _{DSS}		0.25	4.0	μΑ
	V _{GS} = 0 V, V _{DS} = 32 V, T _J = 150°C (Note 5)			1.1	20	
Gate Input Current	V _{DS} = 0 V, V _{GS} = 5.0 V	I _{GSSF}		50	100	μΑ
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 150 \mu A$	V _{GS(th)}	1.3	1.8	2.2	V
Gate Threshold Temperature Coefficient		V _{GS(th)} /T _J		4.0	6.0	-mV/°C
Static Drain-to-Source On-Resistance	V _{GS} = 10 V, I _D = 1.7 A, T _J = 25°C	R _{DS(on)}		165	200	mΩ
	V _{GS} = 10 V, I _D = 1.7 A, T _J = 150°C (Note 5)			305	400	
	$V_{GS} = 5.0 \text{ V}, I_D = 1.7 \text{ A}, T_J = 25^{\circ}\text{C}$			195	230	
	V _{GS} = 5.0 V, I _D = 1.7 A, T _J = 150°C (Note 5)			360	460	
	$V_{GS} = 5.0 \text{ V}, I_D = 0.5 \text{ A}, T_J = 25^{\circ}\text{C}$			190	230	
	V _{GS} = 5.0 V, I _D = 0.5 A, T _J = 150°C (Note 5)			350	460	
Source-Drain Forward On Voltage	V _{GS} = 0 V, I _S = 7.0 A	V _{SD}		1.0		V
SWITCHING CHARACTERISTICS (Note 5	5)			•	•	•
Turn-On Time (10% V _{IN} to 90% I _D)		t _{on}		25	30	μs
Turn-Off Time (90% V _{IN} to 10% I _D)	1	t _{off}		120	200	μs
Turn-On Rise Time (10% I _D to 90% I _D)	V _{GS} = 10 V, V _{DD} = 12 V,	t _{rise}		20	25	μs
Turn-Off Fall Time (90% I _D to 10% I _D)	$I_D = 2.5 \text{ A}, R_L = 4.7 \Omega$	t _{fall}		50	70	μs
Slew-Rate ON (70% V _{DS} to 50% V _{DD})	1	-dV _{DS} /dt _{ON}		0.8	1.2	V/µs
Slew-Rate OFF (50% V _{DS} to 70% V _{DD})	1	dV _{DS} /dt _{OFF}		0.3	0.5	
SELF PROTECTION CHARACTERISTICS	(N _J = 25°C unless otherwise noted)	ote 4)				
Current Limit	$V_{DS} = 10 \text{ V}, V_{GS} = 5.0 \text{ V}, T_{J} = 25^{\circ}\text{C}$	I _{LIM}	3.7	4.3	5.0	Α
	V _{DS} = 10 V, V _{GS} = 5.0 V, T _J = 150°C (Note 5)		2.3	3.0	3.7	
	V _{DS} = 10 V, V _{GS} = 10 V, T _J = 25°C		4.2	4.8	5.4	
	V _{DS} = 10 V, V _{GS} = 10 V, T _J = 150°C (Note 5)		2.7	3.6	4.5	
Temperature Limit (Turn-off)	V _{GS} = 5.0 V (Note 5)	T _{LIM(off)}	150	175	200	°C
Thermal Hysteresis	V _{GS} = 5.0 V	$\Delta T_{LIM(on)}$		15		
Temperature Limit (Turn-off)	V _{GS} = 10 V (Note 5)	T _{LIM(off)}	150	165	185	
Thermal Hysteresis	V _{GS} = 10 V	$\Delta T_{LIM(on)}$		15		
GATE INPUT CHARACTERISTICS (Note 5	5)					
Device ON Gate Input Current	V _{GS} = 5 V I _D = 1.0 A	I _{GON}		50		μΑ
	V _{GS} = 10 V I _D = 1.0 A			400		
Current Limit Gate Input Current	V _{GS} = 5 V, V _{DS} = 10 V	I _{GCL}		0.05		mA
	V _{GS} = 10 V, V _{DS} = 10 V			0.4		
Thermal Limit Fault Gate Input Current	V _{GS} = 5 V, V _{DS} = 10 V	I _{GTL}		0.15		mA
	V _{GS} = 10 V, V _{DS} = 10 V			0.7		
ESD ELECTRICAL CHARACTERISTICS	$(T_J = 25^{\circ}C \text{ unless otherwise noted})$ (Not	te 5)				
Electro-Static Discharge Capability	Human Body Model (HBM)	ESD	4000			V
	Machine Model (MM)	1	400		1	-

- Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Fault conditions are viewed as beyond the normal operating range of the part.
- 5. Not subject to production testing.

TYPICAL PERFORMANCE CURVES

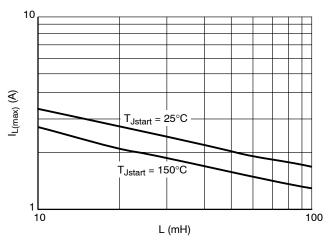


Figure 2. Single Pulse Maximum Switch-off Current vs. Load Inductance

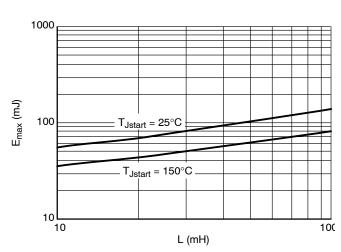


Figure 3. Single Pulse Maximum Switching Energy vs. Load Inductance

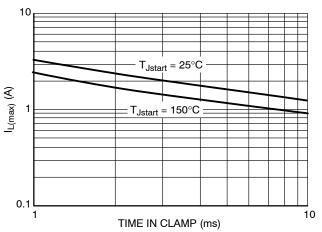


Figure 4. Single Pulse Maximum Inductive Switch-off Current vs. Time in Clamp

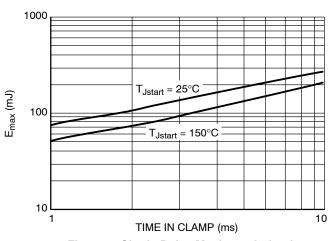


Figure 5. Single Pulse Maximum Inductive Switching Energy vs. Time in Clamp

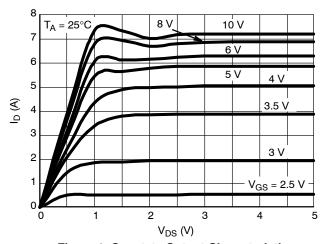


Figure 6. On-state Output Characteristics

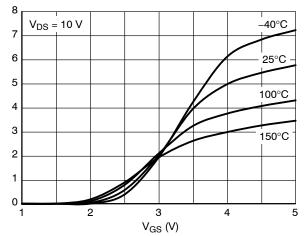


Figure 7. Transfer Characteristics

I_D (A)

TYPICAL PERFORMANCE CURVES

I⊔M (A)

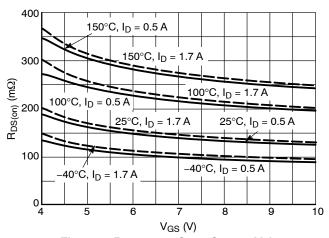


Figure 8. $R_{DS(on)}$ vs. Gate-Source Voltage

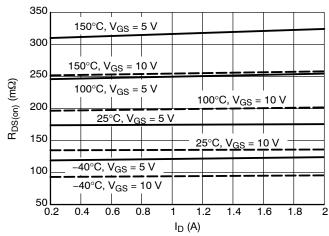


Figure 9. R_{DS(on)} vs. Drain Current

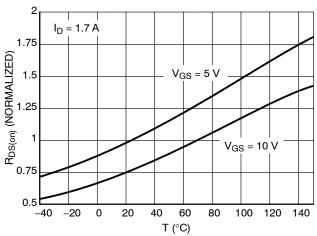


Figure 10. Normalized R_{DS(on)} vs. Temperature

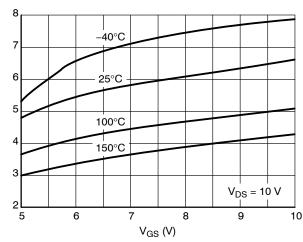


Figure 11. Current Limit vs. Gate-Source Voltage

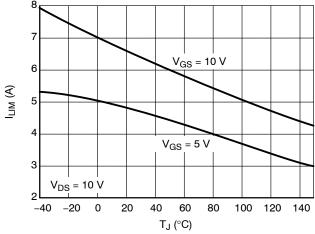


Figure 12. Current Limit vs. Junction Temperature

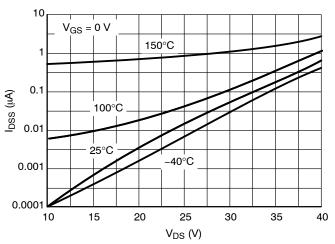


Figure 13. Drain-to-Source Leakage Current

TYPICAL PERFORMANCE CURVES

DRAIN-SOURCE VOLTAGE SLOPE (V/µs)

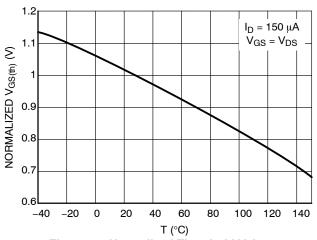


Figure 14. Normalized Threshold Voltage vs. Temperature

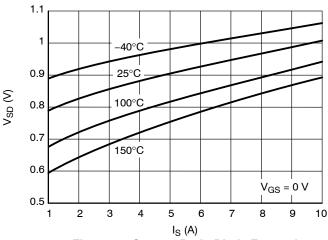


Figure 15. Source-Drain Diode Forward Characteristics

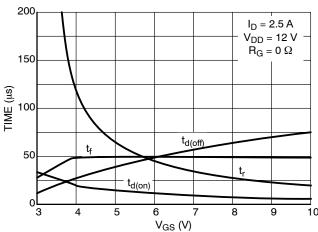


Figure 16. Resistive Load Switching Time vs.
Gate-Source Voltage

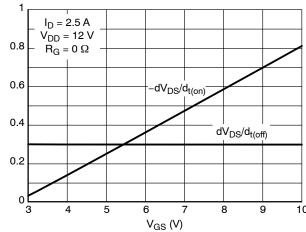


Figure 17. Resistive Load Switching
Drain-Source Voltage Slope vs. Gate-Source
Voltage

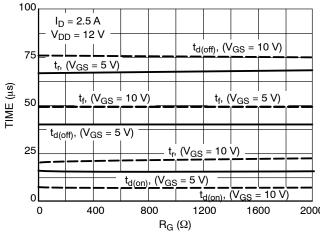


Figure 18. Resistive Load Switching Time vs.
Gate Resistance

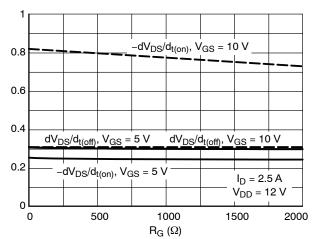


Figure 19. Drain-Source Voltage Slope during Turn On and Turn Off vs. Gate Resistance

DRAIN-SOURCE VOLTAGE SLOPE (V/μs)

TYPICAL PERFORMANCE CURVES

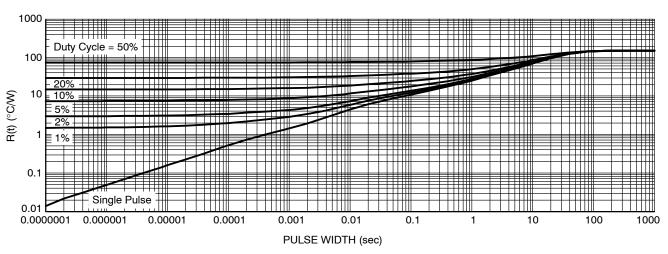


Figure 20. Transient Thermal Resistance

TEST CIRCUITS AND WAVEFORMS

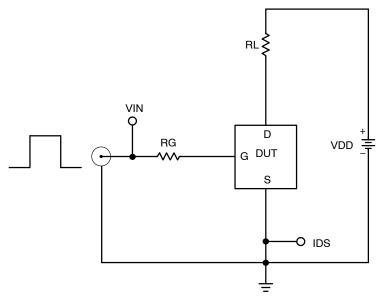


Figure 21. Resistive Load Switching Test Circuit

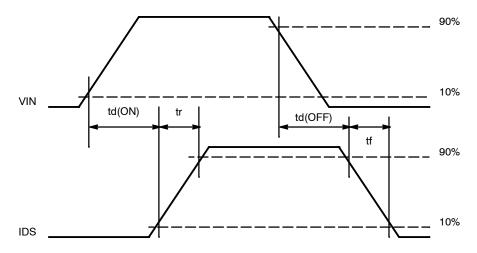


Figure 22. Resistive Load Switching Waveforms

TEST CIRCUITS AND WAVEFORMS

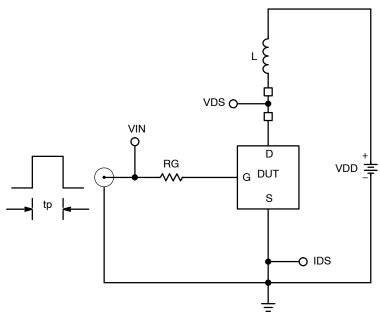


Figure 23. Inductive Load Switching Test Circuit

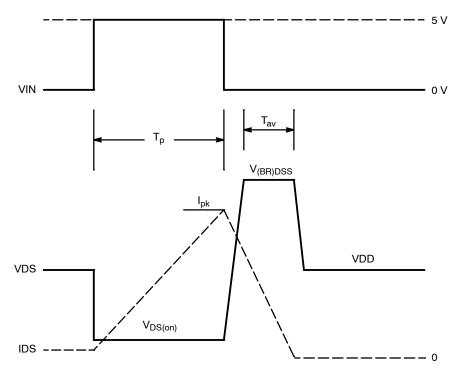
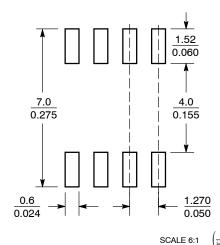


Figure 24. Inductive Load Switching Waveforms

PACKAGE DIMENSIONS

SOIC-8 CASE 751-07 **ISSUE AK** -X-В $|\Phi$ 0.25 (0.010) M -Y-G С SEATING PLANE -Z-0.10 (0.004) 0.25 (0.010) M Z Y S XS

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER DIMENSION A AND B DO NOT INCLUDE

- MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

STYLE 11:

SOURCE 1 PIN 1.

- 2 GATE 1
- SOURCE 2 3.
- GATE 2 DRAIN 2
- 5. 6. DRAIN 2
- DRAIN 1
- DRAIN 1

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